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elnfochips offers Multimedia Kit which interfaces with elnfochips ElC-i.MX93-210 development kit for quick prototyping of multimedia solutions. This kit supports connectivity of Audio IN/OUT, 5.5" 1080 x1920p (FHD) resolution display with touch screen support, 1.0MP MIPI Camera (RPi-CAM-MIPI) developed by NXP & M.2 Key E type connector. It interfaces with EIC-i.MX93-210 development kit through High-Speed Connectors (HS1 & HS2) and Low-Speed Interface connector.

#### Multimedia Kit Features

#### Audio Interfaces

- 2x on board Analog Mic Input
- 2x 1W Speaker Out
- 1x 3.5mm Audio Jack
- 2x Digital PDM Mic input

### Camera Interface

- Provides connectivity of 1.0MP CSI camera module "RPI-CAM-MIPI" designed by NXP
- 22-pin/0.5mm FPC/FFC connector interface to connect with "RPI-CAM-MIPI"

## 2 Key-E Type connector support

- Provide connectivity of M.2 Key E Type externa WLAN module
- Supports multiple interfaces SDIO, PCM, UART, USB, I2C

# Display Interface

- Interface Type: 4 Lane MIPI DSI
- LCD Type: IPS TFT (16.7M)/ Transmissive
- Backlight Type: White LED (14\*LED)
- Display Resolution: 1080 x 1920 (Maximum)
- Framerate supported: 60
- Bit Per Pixel (BPP): 24
- Pixel stream type: Packed pixel stream, RGB888 (24 bits per pixels)
- LCD-Active area Outline dimensions (W x H): 68.04mm(W) x 120.96mm(H)
- Pixel pitch 0.063mm x 0.063mm
- System Interface
  - Display Data: 4 Lane MIPI DSI
  - Touch: I2C
  - Control: GPIOs
- Mezzanine to Display Board Cable: 40 pins FFC Cable
- Supply Voltages
  - O Display: 2.8V for VCC, 1.8V for I/O
  - O Touch: 3.3V for VCC, 1.8V IO
- Operating Temperature: -20°C ~50°C

# **Multimedia Kit Dimensions**

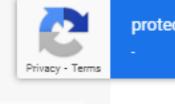
85mm x 54mm

#### NXP

- > MPC830X-MPC8306 SOM
- > MPC830X-MPC8308 SOM
- > MPC830X-MPC8309 SOM
- > i.MX6
- > i.MX 8X based AI-ML Board
- > i.MX 8M based Thor96 Board
- > NXPS32 Platform Experience

> i.MX93X Reference Development Platform

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